

GSE033LD4DNF

ESD Protection Diode

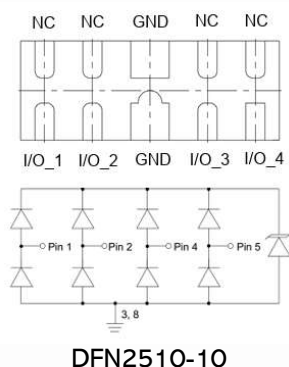
Product Description

It is designed to protect sensitive electronics from damage or latch up due to ESD, lightning, and other voltage induced transient events.

Features

- Up to 4 I/O Lines Protection
- Peak Pulse Power : 40W (8/20μs)
- Operating Voltage : 3.3V
- Low Leakage Current: nA Level
- Low Capacitance: 0.34pF Max.
- IEC61000-4-2(ESD) ±25kV (air)
- IEC61000-4-2(ESD) ±20kV (contact)
- IEC61000-4-5(Lighting) 3A (8/20μs)
- RoHS Compliant

Package & Device Schematic



Applications

- High Speed Line: USB1.0/2.0, VGA, DVI, SDI
- Serial and Parallel Ports
- Notebooks, Desktops, Servers
- Cellular handsets and accessories
- Portable instrumentation
- Peripherals

Ordering Information & Marking Code

| Part Number | Package | Quantity | Marking Code |
|--------------|------------|----------|--------------|
| GSE033LD4DNF | DFN2510-10 | 3KPCS | 332P |



332P = Product Code
Dot denotes Pin1

GSE033LD4DNF

Absolute Maximum Ratings

(T_A=25°C unless otherwise specified)

| Symbol | Parameter | Typical | Unit |
|------------------|---|-------------|------|
| P _{PP} | Peak Pulse Power (t _p =8/20μs) | 40 | W |
| I _{PP} | Peak Pulse Current (t _p =8/20μs) | 3 | A |
| V _{ESD} | ESD Per IEC61000-4-2 (Air) | ±25 | KV |
| | ESD Per IEC61000-4-2 (Contact) | ±20 | KV |
| T _J | Operating Junction Temperature Range | -55 to +125 | °C |
| T _{STG} | Storage Temperature Range | -55 to +150 | °C |

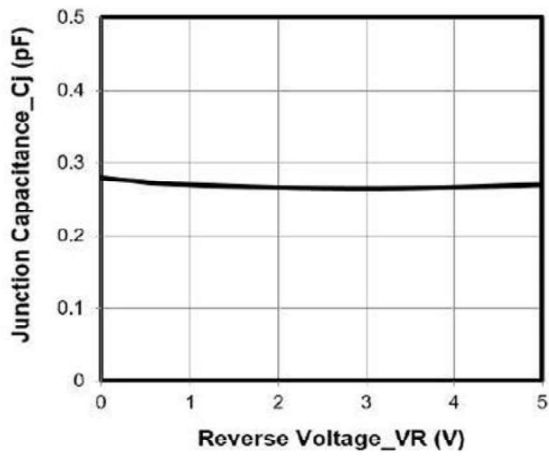
Note : Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Electrical Characteristics

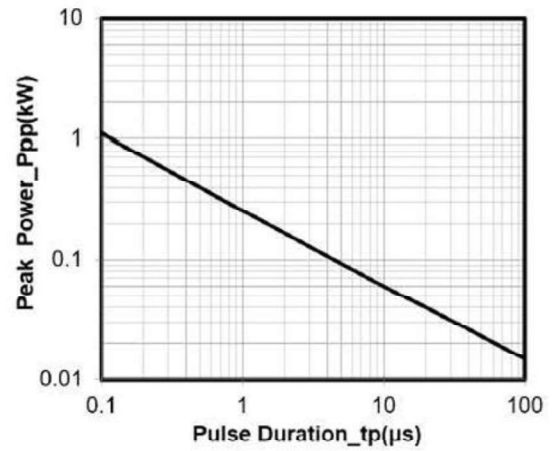
(T_A=25°C, for any I/O pin to ground unless otherwise specified)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|---------------------------|------------------------------|-----|-----|------|------|
| V _{RWM} | Reverse Working Voltage | - | | | 3.3 | V |
| V _{BR} | Reverse Breakdown Voltage | I _R =1mA | 5.5 | | 7.5 | V |
| I _R | Reverse Leakage Current | V _{RWM} =3.3V | | | 0.5 | μA |
| V _C | Clamping Voltage | I _{PP} =1A (8/20μs) | | | 9 | V |
| | | I _{PP} =3A (8/20μs) | | | 13 | V |
| C _J | Junction Capacitance | V _R =1.5V, f=1MHz | | | 0.34 | pF |

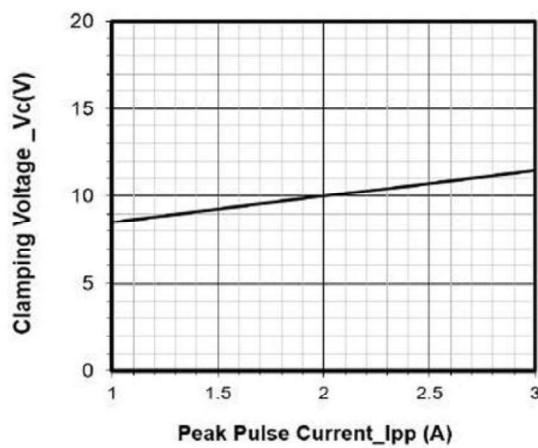
Typical Characteristics (TA=25°C unless otherwise specified)



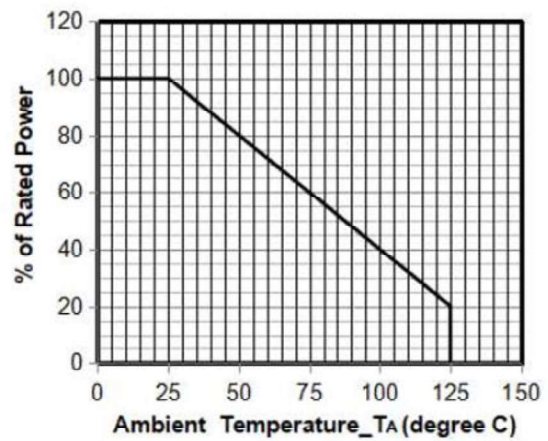
Junction Capacitance vs. Reverse Voltage



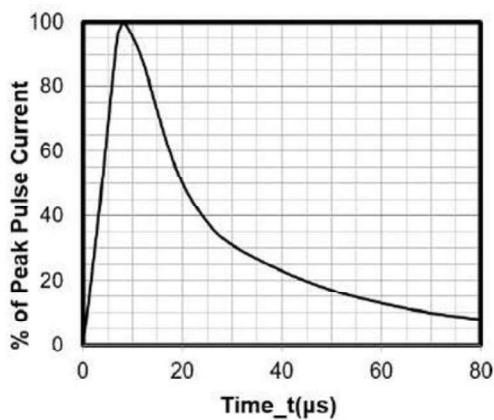
Peak Pulse Power vs. Pulse Time



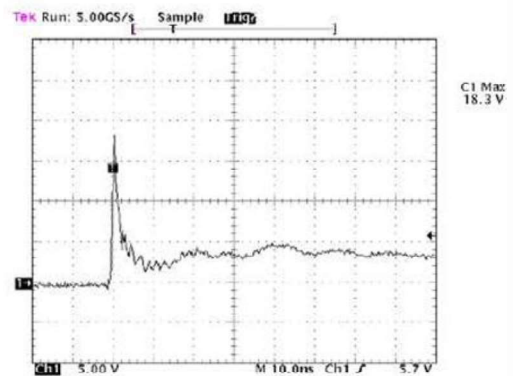
Clamping Voltage vs. Peak Pulse Current



Power Derating Curve



8 X 20μs Pulse Waveform



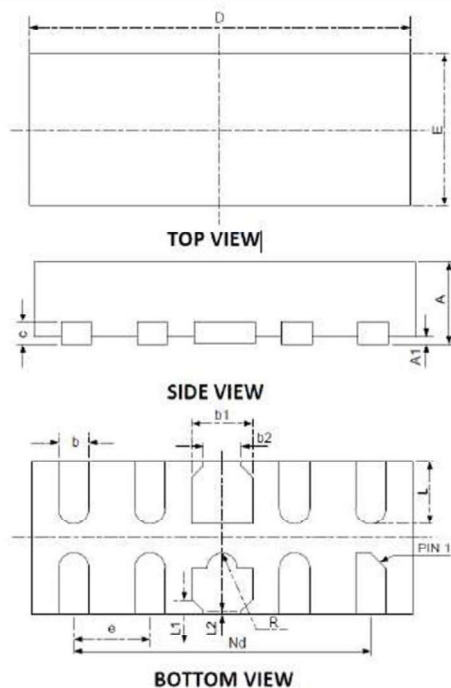
Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

8 kV Contact per IEC61000-4-2

Package Dimension

DFN2510-10







| SYM | DIMENSIONS | | | | | |
|-----|-------------|------|------|----------|-------|-------|
| | MILLIMETERS | | | INCHES | | |
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| A1 | 0.00 | 0.02 | 0.05 | 0.000 | 0.001 | 0.002 |
| b | 0.15 | 0.20 | 0.25 | 0.006 | 0.008 | 0.010 |
| b1 | 0.35 | 0.40 | 0.45 | 0.014 | 0.016 | 0.018 |
| b2 | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| c | 0.10 | 0.15 | 0.20 | 0.004 | 0.006 | 0.008 |
| D | 2.45 | 2.50 | 2.55 | 0.098 | 0.100 | 0.102 |
| e | 0.50BSC | | | 0.020BSC | | |
| Nd | 2.00BSC | | | 0.080BSC | | |
| E | 0.95 | 1.00 | 1.05 | 0.038 | 0.040 | 0.042 |
| L | 0.35 | 0.40 | 0.45 | 0.014 | 0.016 | 0.018 |
| L1 | 0.075REF | | | 0.003REF | | |
| L2 | 0.050REF | | | 0.002REF | | |
| h | 0.08 | 0.12 | 0.15 | 0.003 | 0.005 | 0.006 |
| R | 0.05 | 0.10 | 0.15 | 0.002 | 0.004 | 0.006 |

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CONTACT US

| GS Headquarter | |
|---|--|
|  | 4F.,No.43-1,Lane11,Sec.6,Minquan E.Rd Neihs District Taipei City 114, Taiwan (R.O.C) |
|  | 886-2-2657-9980 |
|  | 886-2-2657-3630 |
|  | sales_twn@gs-power.com |

| RD Division | |
|---|--------------------------------------|
|  | 824 Bolton Drive Milpitas. CA. 95035 |
|  | 1-408-457-0587 |